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(71) Applicant *(for all designated States except US)*: **ADVANCED MICRO DEVICES, INC.** [US/US]; ONE AMD PLACE, MAIL STOP 68, P.O. BOX 3453, Sunnyvale, CA 94088-3453 (US).

(72) Inventors; and

(75) Inventors/Applicants *(for US only)*: **PREUSSE, Axel** [DE/DE]; HUMBOLDTSTRASSE 3, 01445 Radebeul (DE). **WEHNER, Susanne** [DE/DE]; RUDOLFSTR 23B, 01097 Dresden (DE). **NOPPER, Markus** [DE/DE]; D0EBELNER STRASSE 67G, 01129 Dresden (DE).

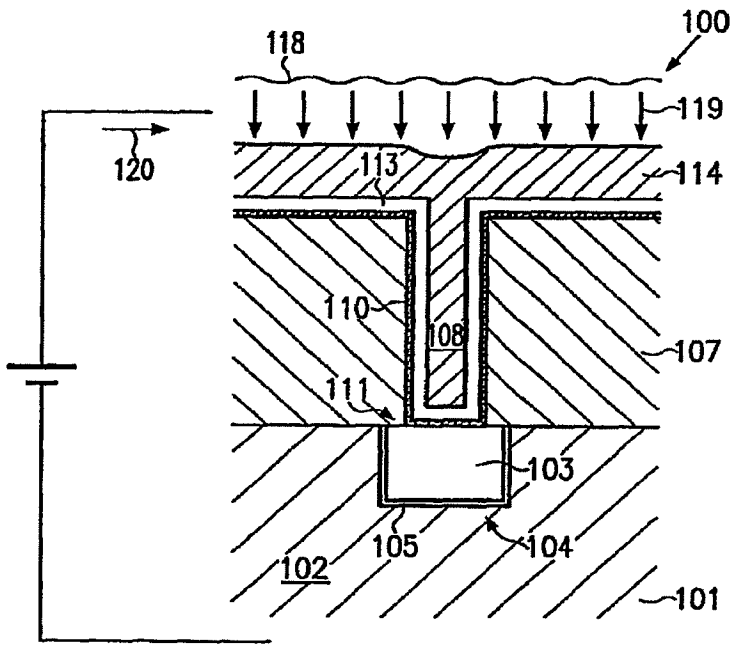
(74) Agent: **DRAKE, Paul, S.**; ADVANCED MICRO DEVICES, INC., 5204 EAST BEN WHITE BOULEVARD, MAIL STOP 562, Austin, TX 78741 (US).

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(54) Title: METAL LAYER OVER A PATTERNED DIELECTRIC BY WET CHEMICAL DEPOSITION INCLUDING AN ELECTROLESS AND A POWERED PHASE



(57) Abstract: By performing an electroless deposition and an electro deposition process in situ, highly reliable metallizations may be provided, wherein limitations with respect to contaminations and device scaling, encountered by conventional chemical vapor deposition (CVD), atomic layer deposition (ALD) and physical vapor deposition (PVD) techniques for the formation of seed layers may be overcome. In some embodiments, a barrier layer is also deposited on the basis of a wet chemical deposition process.

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